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C

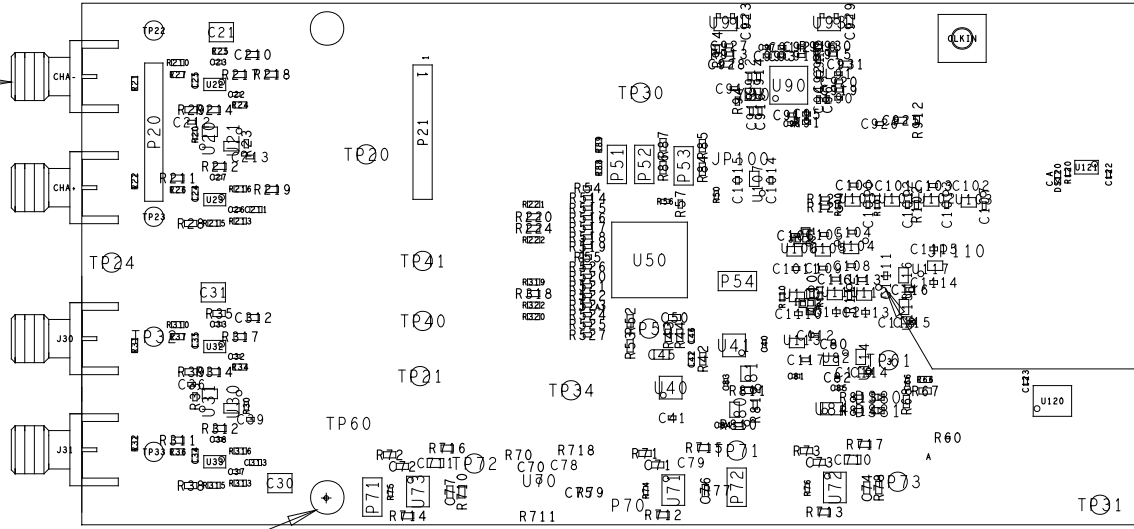
B

A

ETCH TO EDGE 3 MILS.
SOLDER FILLET BOARD ETCH TO
CONNECTOR TOP AND BOTTOM.
4 PLACES

SEE NOTE 5
FOR SCREW AND STANDOFF INSTALLATION.
(2 PLACES)

SEE NOTE 4




REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	INITIAL RELEASE		

ASSEMBLY NOTES:

- BOARD ACCEPTABILITY PER ANALOG DEVICES, INC. SPECIFICATION TST00119 (LATEST REVISION).
- REPAIRS PER IPC-7711/21(LATEST REVISION) ARE ALLOWED.
- REPAIRS ARE NOT ALLOWED IN SOLDERMASK FREE AREAS ON EITHER SIDE OF THE BOARD.
- AD4880 TO BE SUPPLIED AND FITTED
- INSTALL STUD (N070648) ON PRIMARY SIDE AND STANDOFF (N070649) ON THE SECONDARY SIDE.
- RoHS COMPLIANCE: ASSEMBLY VENDOR SHOULD ASSURE COMPLIANCE WITH LEAD-FREE AND RoHS PCB ASSEMBLY STANDARDS (EU RoHS DIRECTIVE 2002/95/EC).
- BOARDS TO BE SHIPPED SINGULATED AFTER ASSEMBLY PROCESS. SMOOTHEN EDGES AND FREE FROM BURRS AFTER DEPANELIZATION PROCESS.
- SHUNTS TO BE PLACED ON P51,P52,P53,P54 PLUS ONE SHIPPED LOOSE.

PRIMARY SIDE

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMALS FRACTIONS ANGLES .XX -.010 --1/32 -- 2 .XXX -.005 .XXXX -.0050	APPROVAL		DATE		 <div>ANALOG DEVICES</div>	WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887				
	TEMPLATE ENGINEER					TITLE ASSEMBLY EVAL - AD488x FMCZ CUSTOMER EVAL BOARD Z				
	HARDWARE SERVICES M. VICEDO		02FEB22							
	HARDWARE SYSTEMS									
MATERIAL	TEST ENGINEER									
	COMPONENT ENGINEER A. GIRON		02FEB22							
	TEST PROCESS									
	HARDWARE RELEASE K. JABATAN		02FEB22							
FINISH	DESIGNER M. VICEDO		02FEB22		SIZE C	FSCM NO 24355	DRAWING NUMBER 01	REV B		
	PTD ENGINEER S. KOWALIK		02FEB22							
	CHECKER									
DO NOT SCALE DWG				SCALE 1/1				SHEET 1 OF 2		

ART FILM - array2



2

1

D

D

C

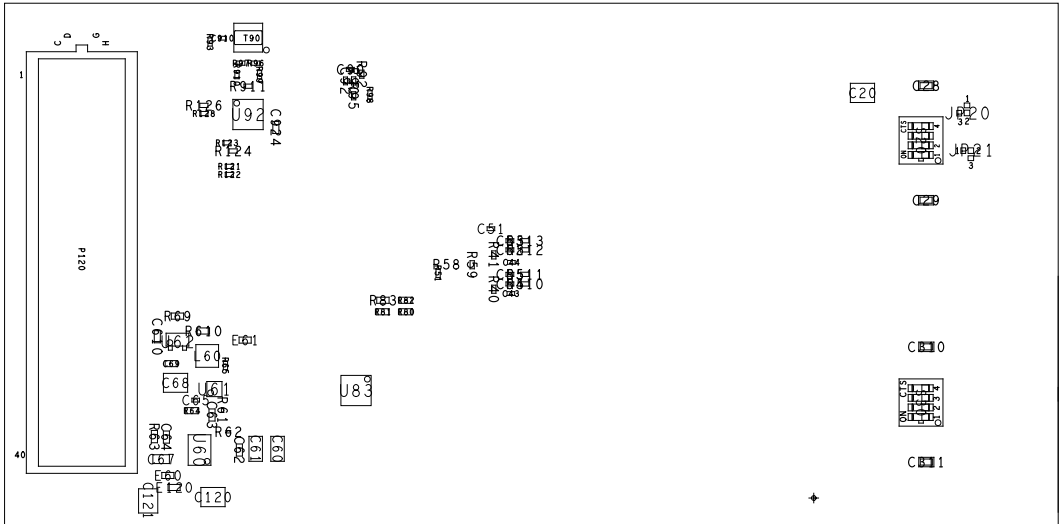
C

B

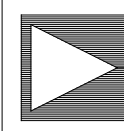
B

A

A



SECONDARY SIDE

 ANALOG DEVICES <div>WWM DIVISION 804 WOBURN STREET WILMINGTON, MA 01887</div>			
SIZE	FSCM NO	DRAWING NUMBER	REV
C	24355	01-083437	B
SCALE	1/1	SHEET 2 OF 2	

1

2



ART FILM - array2

3

4

3

4